



PCN Number:

July 2015

Product/Process Change Notification (PCN)

Customer: Digi-Key

Date: July 20, 2015

Catalog / Customer Part # and/or Lot# affected: A4403GEUTR-T

Originator: J. Hurley Phone: 508.854.5431 Email: Jhurley@allegromicro.com

Duration of Change:

Permanent [X] Temporary (explain) []

Summary description of change:

Part Change: [X] Process Change: [] Other: []

- 1. The A4403GEUTR-T will change from being manufactured on the 6" wafer line at wafer fab, Polar Semiconductor LLC (PSL), Bloomington, MN, USA utilizing ABCD4 technology to the 8" wafer line at Polar Semiconductor LLC (PSL), Bloomington, MN, USA utilizing ABCD4-8 technology.
2. The A4403GEUTR-T will change from being manufactured with Gold Bond Wires at Carsem China to being manufactured with Copper Bond Wires at Carsem China.
3. The A4403GEUTR-T will change from Final Test at Allegro MicroSystems, Inc. Manila, Philippines (AMPI) to Final Test at Allegro MicroSystems Thailand, Company Ltd. (AMTC)

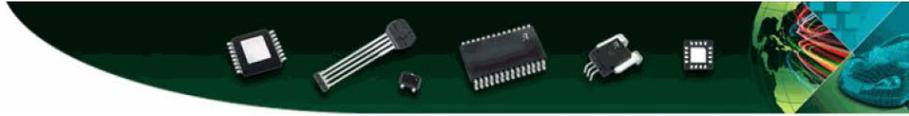
What is the part or process changing from (provide details)?

- 1. Allegro currently manufactures the A4403GEUTR-T on the 6" wafer line at wafer fab, Polar Semiconductor LLC (PSL), Bloomington, MN, USA, utilizing ABCD4 technology.
2. The A4403GEUTR-T is manufactured with Gold Bond Wires at Carsem China.
3. Allegro currently final tests the A4403GEUTR-T at Allegro MicroSystems, Inc. Manila, Philippines (AMPI)

What is the part or process changing to (describe the anticipated impact of this change on form, fit and/or function)?

- 1. The A4403GEUTR-T will be manufactured on the 8" wafer line at wafer fab, Polar Semiconductor LLC (PSL) Bloomington, MN, USA, utilizing ABCD4-8 technology.
2. The A4403GEUTR-T will be manufactured with Gold Bond Wires at Carsem China.
3. Allegro will be expanding its manufacturing capabilities with the addition of a new, wholly-owned integrated circuit test facility located in Saraburi, Thailand. The same make and model test equipment will be utilized and test site transfer buy off data will be on file for each device before production begins.

Note: Validation of equivalence within a specific application is at the discretion of the Customer.



Expected completion date for internal qualification: Wafer fab and Assembly Complete

The same make and model test equipment will be utilized and test site transfer buy off data will be on file for each device before production begins.

Expected PPAP availability date: N/A

Target implementation date: September 1, 2015

Estimated date of first shipment: October 1, 2015

Expected sample availability date: June 2015.

Customer Approval Required: Yes **Date Required:**
No **Notification Only**

Please note: It is our intention to inform our customer of changes as early as possible. Under Allegro’s procedure for product/process change notification, Allegro strives, based on its technical judgment, to provide notification of significant changes that may affect form, fit or function. However, as Allegro cannot ensure evaluation of product/process changes for each and every application; the customer retains responsibility to validate the impact of a change on its application suitability. If samples are needed for validation of a change, requests may be made via the contact information provided herein. Please contact your Account Manager or local Sales contact for any questions. We would kindly request your consideration so we can meet our target date for implementation. Unless both parties agree to extend the implementation date, this change will be implemented as scheduled.

Customer comments/Conditions of Acceptance:

Approved by: _____ Date: _____ Title: _____
cc: Allegro Sales/Marketing/Quality